

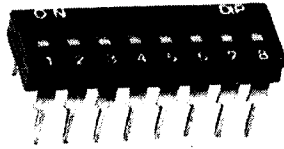
DIL switches

Order code	Manufacturer code	Description
80-0115	n/a	2 WAY 4 PIN LP DIL SWITCH RC
80-0120	n/a	4 WAY 8 PIN LP DIL SWITCH RC
80-0125	n/a	8 WAY 16 PIN LP DIL SWITCH (RC)

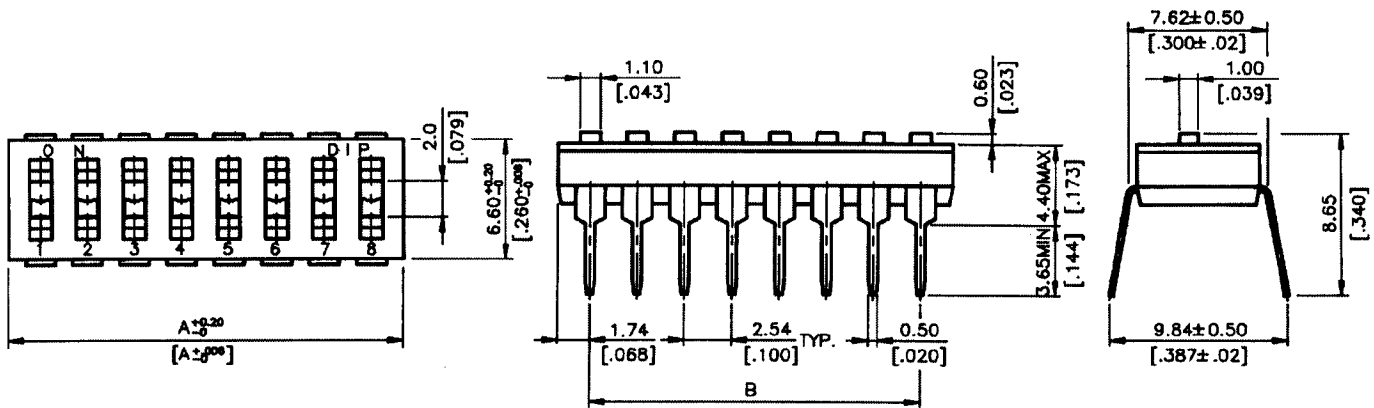
DIL switches	Page 1 of 3
The enclosed information is believed to be correct, Information may change without notice due to product improvement. Users should ensure that the product is suitable for their use. E. & O. E.	Revision A 20/02/2007

Low Profile DIL Switches

Photograph



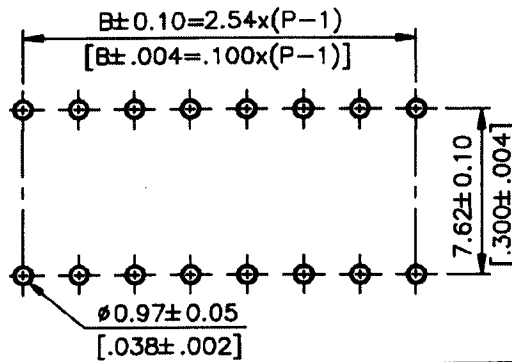
Technical Drawings



Additional Information

Switches	No. of Pins (DIL)	Dimensions mm [in.]	
		A	B
2	4	6.02 [.237]	2.54 [.100]
4	8	11.10 [.437]	7.62 [.300]
8	16	21.26 [.837]	17.78 [.700]

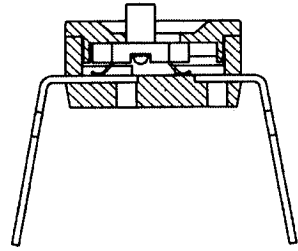
PCB Layout Information



Construction of Switch

Materials

Base/Cover	:	UL94V-0 PBT + Glass Fibre Reinforced (Colour Black)
Actuators	:	UL94V-0 Nylon + Glass Fibre Reinforced (Colour White)
Contact	:	Copper Alloy
Terminal	:	Brass
Contact Plating	:	3 μ in. gold plating over 40 μ in. nickel.
Terminal Plating	:	90/10 Solder



Mechanical

Mechanical Life	:	2000 operations min. per switch
Operation Force	:	800g max.
Stroke	:	1.0mm
Operating Temperature	:	-40°C to 85°C
Storage Temperature	:	-40°C to 85°C
Vibration Test	:	MIL-STD-202F Method 201A Frequency : 10-55-10Hz/1 min. Directions : X, Y, Z, three mutually perpendicular directions. Time : 2 Hours each direction
Shock Test	:	MIL-STD-202F Method 213B Condition A. Gravity : 50g (peak), 11mS Direction : 6 Sides (3 Times)

Electrical

Electrical Life	:	2000 operations min. per switch (24Vdc @ 25mA)
Non-Switching Rating	:	100mA , 50Vdc
Switching Rating	:	25mA , 24Vdc
Contact Resistance	:	50 m Ω max. at initial (current @ 100mA) 100m Ω max. at life test.
Insulation Resistance	:	(at voltage DC500V \pm 15V) 100M Ω min. between adjacent terminals.
Dielectric Strength	:	500Vdc / 1 minute.
Capacitance	:	5pF max. between adjacent terminals.
Circuit	:	Single Pole Single Throw.

Soldering and Cleaning Processes

It is recommended that the switches be in the "OFF" position for the following operations.

▪ **WAVE SOLDERING**

Solder Temperature : 260°C max. 5 sec's.

▪ **HAND SOLDERING**

Soldering Iron : 30 Watts or less
Soldering Temperature : 320°C max. 3 sec's.

▪ **CLEANING PROCESS**

Flux clean using force rinse, high agitation or triple bath cleaning method Freon TF or TE give good results. When vapour methods are used, do not subject the switch to solvents at temperatures above 51°C.